



Material Content Data Sheet



Sales Product Name		BSC050N03LS G		Issued		20. July 2018		
MA#		MA001508102						
Package		PG-TDSON-8-40		Weight*		118.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.213	1.02	1.02	10213	10213
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.81	31.85	318049	318463
wire	non noble metal	copper	7440-50-8	0.062	0.05	0.05	522	522
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		724	
	plastics	epoxy resin	-	6.788	5.72		57173	
	inorganic material	silicondioxide	60676-86-0	36.088	30.40	36.19	303956	361853
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12227	12227
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1394	1394
solder	noble metal	silver	7440-22-4	0.035	0.03		297	
	non noble metal	tin	7440-31-5	0.028	0.02		237	
	non noble metal	lead	7439-92-1	1.345	1.13	1.18	11330	11864
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.53	9.54	95344	95468
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.78	18.81	187752	187996
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com